Title (en)

A microporous layer for lowering friction in metal forming processes

Title (de)

Mikroporöse Schicht zur Minderung der Reibung bei Metallverformungsprozessen

Title (fr)

Couche microporeuse pour diminuer la friction dans un procédé de formage de métaux

Publication

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Application

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Priority

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Abstract (en)

The invention is a microporous layer to be used in metal forming processes providing lower friction and improved resistance against galling. The layer is a thin, porous metallic film, which is electrochemically deposited on a metallic substrate, whereafter one of the metals of the deposited film is selectively removed by chemical etching, thereby leaving a micro- or even nanoporous layer on the surface of the substrate, which enhances lubricant entrapment leading to improved lubrication during metal forming processes.

IPC 8 full level

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Citation (search report)

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